© Copy	rial Compositio yright 2005. IPC, Ba tional and Pan-Amer	nnockbur	rn, Illinois. A	ll rights reserved utions.	under both	This docum level parts, t	ent is a decla he declaratio	ration of th n encompa	ne substance asses all low	s within the er level mat	manufactur erials for wh	er listed ite hich the m	em. Note: anufactur	if the item is an a er has engineering	assembly with lower g responsibility.	
					Form Type Distribute						eous Materia	ials and Mfg Information				
Supplier Information																
Company name*			Company unique ID			Unique ID Authority					Response Date*					
On Semiconductor											2021-02-04					
Contact Name			Title - Contact				Phone - Contact*					Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Requester Item Nu	ster Item Number Mfr Iten		n Number Mfr Item Name				Effective D	ate Vers	ion Manufacturing Site		v	Veight*	UOM	Unit Type		
	N.	NJVMJD112T4G		BIP DPAK NPN 2A 100V TR			2021-02-04			VN5		3	50.99	mg	Each	
Manufacturing Procces	s Information															
Terminal Plating / Grid Array Material Termin		minal Base A	Base Alloy J-STD-020 MSL Rat		L Rating	Peak Process Body Temperature Ma		ure Max Ti	me at Peak	ak Temperature Numb		nber of Reflow C	cles			
Matte Tin (Sn) - annealed CU Alle			Alloy		1		260		С	30		second	ls 3			
Comments																
level 1 - maximum time at pea	ak temperature dur	ring solde	ering is 10-3	0 seconds												
For more information regard	ling material compo	sition ple	ease refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	1.4	mg	А	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame	214.64	mg	В	Nickel (Ni)	7440-02-0		0.4293	mg
			Supplier	Copper (Cu)	7440-50-8		214.2107	mg
Mold Compound-Black	129.65	mg		Phenolic Resin	proprietary data		10.372	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		10.372	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		108.2577	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Al	1.37	mg	Supplier	Aluminum (Al)	7429-90-5		1.37	mg